

**27~29 July, 2023. Seoul, Korea**

**Application Form**

|  |  |  |  |
| --- | --- | --- | --- |
| **\* COUNTRY** |  | **\* CITY** |  |
| **\* INVENTOR** | **NAME** | **SCHOOL / COMPANY NAME** |
| 1.  |  |
| 2. |  |
| 3. |  |
| 4. |  |
| 5. |  |
| **Write the correct English name and affiliation name / Up to 5 People** |
| **Agency** **(Contact)****or Contact Participant** | **Name** |  |
| **Tel** |  |
| **E-mail** |  |
| **Add** |  |

 **. . 2023**

**Send to here**: E-mail / Lee37895661@gmail.com / 7935111@naver.com

Date : \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

|  |  |
| --- | --- |
| **\*Name of Invention** |  |
| **\*Abstract Of Invention & Photo of Invention** |  |